# International Rectifier

# IRFK6H450,IRFK6J450

## Isolated Base Power HEX-pak<sup>TM</sup> Assembly - Parallel Chip Configuration

- · High Current Capability.
- · UL recognised E78996.
- · Electrically Isolated Base Plate.
- · Easy Assembly into Equipment.

#### Description

The HEX-pak<sup>TM</sup> utilises the well-proven HEXFET<sup>TM</sup> die, combining low on-state resistance with high transconductance. These superior technology die are assembled by state of the art techniques into the TO-240 package, featuring 2.5kV rms isolation and solid M5 screw connections. The small footprint means the package is highly suited to power applications where space is a premium. Available in two versions, IRFK.H... for fast switching and IRFK.J... for oscillation sensitive applications.

V <sub>DS</sub> = 500V
$R_{DS(on)} = 67m\Omega$
I <sub>D</sub> = 66A

**Absolute Maximum Rating** 

	Parameter	Max.	Units
I <sub>D</sub> @ T <sub>C</sub> =25°C	Continuous Drain Current	66	Α
I <sub>D</sub> @ T <sub>C</sub> =100°C	Continuous Drain Current	42	A
I <sub>DM</sub>	Pulse Drain Current	264	A ①
P <sub>D</sub> @ T <sub>C</sub> =25°C	Maximum Power Dissipation	625	W
V <sub>GS</sub>	Gate-to-Source Voltage	20	V
V <sub>INS</sub>	R.M.S. Isolation Voltage, circuit to base	2.5	kV
T <sub>J</sub>	Operating Junction Temperature Range	-40 to 150	°C
T <sub>STG</sub>	Storage Temperature Range	-40 to 150	°C

Thermal and Mechanical Specifications

	Parameter	Min.	Тур.	Max.	Units
R <sub>thJC</sub>	Junction-to-Case	-	-	0.20	K/W ②
R <sub>thCS</sub>	Case-to-Sink, smooth & greased surface	-	0.1	-	K/W
Tilles	Mounting Torque +10%	-		-	3
	HEXpak to Heatsink	-	5		Nm
	Busbar to HEXpak	-	3	-	Nm
 wt	Approximate Weight	-	140	-	g
		-	5	-	OZ

#### Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature see figure 8.
- 2 Per Module.
- ③ A mounting compound is recommended and the torque should be rechecked after a period of three hours to allow for the spread of the compound.

# Electrical Characteristics @ T<sub>J</sub> = 25°C (Unless otherwise specified)

<u>-</u>	Parameter		Min.	Тур.	Max.	Units	Test Conditions
B <sub>VDSS</sub>	Drain-to-Source Breakdown		500	-	-	\ \	V <sub>GS</sub> =0V, I <sub>D</sub> =1.0mA
R <sub>DS(on)</sub>	Static Drain-to-Source		-	50	67	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =42A
On-State Resistance							
I <sub>D(on)</sub>	On-State Drain Current		66	-	-	A	$V_{DS} > I_{D(on)} \times R_{DS(on)} max,$ $V_{GS}=10V$
V <sub>GS(th)</sub>	Gate Threshold Voltage		2.0	-	4.0	٧	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =1.5mA
g <sub>fs</sub>	Forward Transconductance ④		48	72		S	V <sub>DS</sub> > 50V, I <sub>D</sub> =42A
IDSS	Zero Gate Voltage Drain	Zero Gate Voltage Drain Current		-	1.5	mA	V <sub>DS</sub> =V <sub>DS</sub> max, V <sub>GS</sub> =0v
.088	, and the same of		-	-	6.0	mA	V <sub>GS</sub> =10V, T <sub>C</sub> =125°C,
					•		V <sub>DS</sub> =V <sub>DS</sub> max x 0.8
I <sub>GSS</sub>	Gate-to-Source Leakage	Forward	-	-	600	nA	V <sub>GS</sub> =20V
I <sub>GSS</sub>	Gate-to-Source Leakage		_	-	-600	nA	V <sub>GS</sub> =-20V
Q <sub>q</sub>	Total Gate Charge		-	800	880	nC	I <sub>D</sub> =66A, V <sub>GS</sub> =10V,
Q <sub>gs</sub>	Gate-to-Source Charge		-	70	105	nC	V <sub>DS</sub> =V <sub>DS</sub> max x 0.8
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge		-	260	400	nC	
t <sub>d(on)</sub>	Turn-on Delay Time	IRFK6H450	-	55	-	ns	V <sub>DD</sub> =210V, I <sub>D</sub> =42A,
·d(on)		IRFK6J450	-	65	-	ns	
t <sub>r</sub>	Rise Time	IRFK6H450	-	55	<u> </u>	ns	V <sub>GS</sub> =10V,
		IRFK6J450	-	70	-	ns_	0.00
t <sub>d(off)</sub>	Turn-off Delay Time	IRFK6H450	-	330	-	ns	R <sub>SOURCE</sub> =3.3Ω
		IRFK6J450 IRFK6H450	-	440 70		ns	-
$t_{f}$	Fall Time	IRFK6H450	-	110	<del>                                     </del>	ns	_
L <sub>DS</sub>	Drain-to-Source Inductance		-	18	-	nH	
C <sub>iss</sub>	Input Capacitance		-	8.0	-	nF	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V,
Coss	Output Capacitance		-	2.0	-	nF	f=1.0MHz
C <sub>rss</sub>	Reverse Transfer Capa	citance	-	0.8	-	nF	-
- rss	Linear Derating Factor	<u> </u>	<u> </u>	-	5	W/K	

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Is	Continuous Source Current (Body Diode)	-	-	66	A	
l <sub>SM</sub>	Pulsed Source Current (Body Diode)	-	-	230	A	
V <sub>SD</sub>	Diode Forward Voltage		-	1.4	٧	$V_{GS}=0V$ , $I_{S}=66A$ , $T_{C}=25^{\circ}C$
t <sub>rr</sub>	Reverse Recovery Time	280	580	1200	ns	di/dt=400A/μs, T <sub>J</sub> =150°C
Q <sub>rr</sub>	Reverse Recovered Charge	19.0	42.0	90.0	μC	I <sub>S</sub> =66A

#### Notes:

⊕ - Pulse Width ≤ 300μs; Duty cycle ≤ 2%.

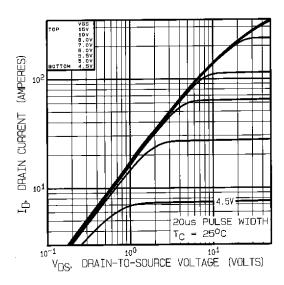


Fig 1. Typical Output Characteristics,  $T_C=25^{\circ}C$ 

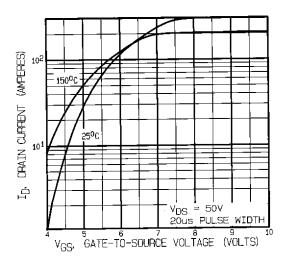


Fig 3. Typical Transfer Characteristics

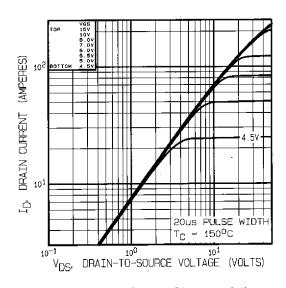


Fig 2. Typical Output Characteristics,  $\rm T_{C}{=}150^{o}C$ 

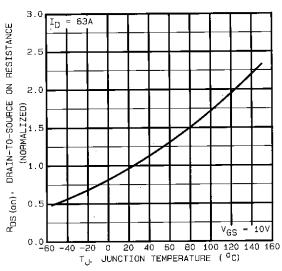


Fig 4. Normalized On-Resistance Vs.
Temperature

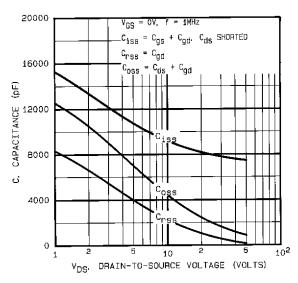


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

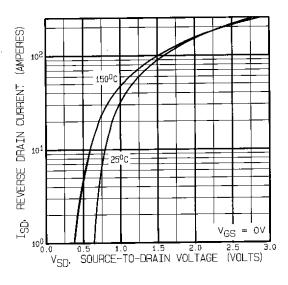
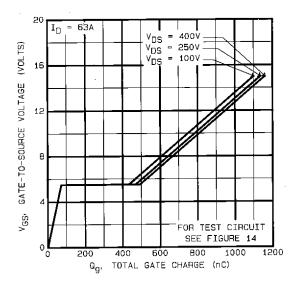


Fig 7. Typical Source-Drain Diode Forward Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage

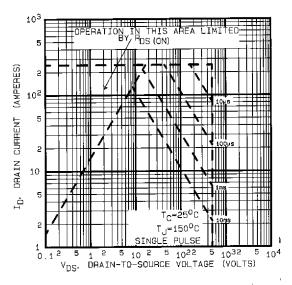


Fig 8. Maximum Safe Operating Area

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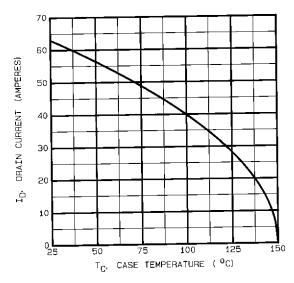


Fig 9. Maximum Drain Current Vs.
Case Temperature

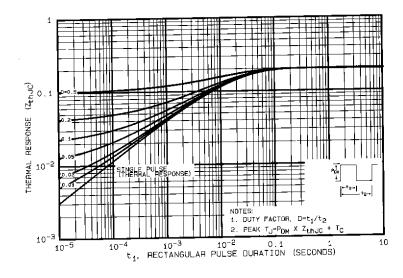


Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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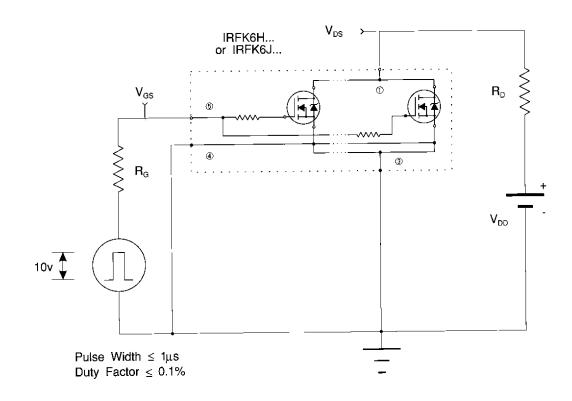


Fig 11a. Switching Time Test Circuit

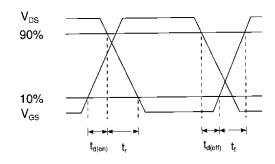
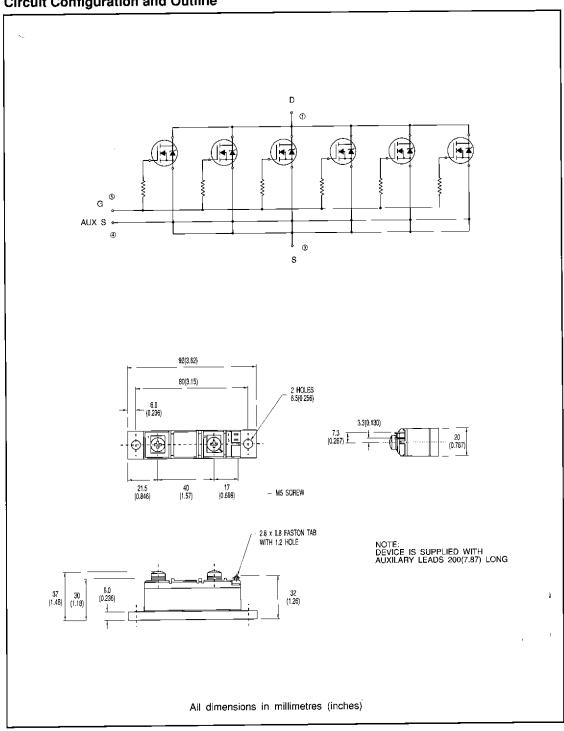
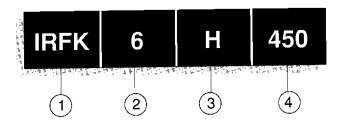


Fig 11b. Switching Time Waveforms

### **Circuit Configuration and Outline**



### **Part Numbering**



- HEX-pak Module.
- Number of HEXFETs in parallel.
- 3. H Fast switching.
  - J Oscillation resistant for sensitive applications.
- 4. Voltage code:-

054 - 60V

150 - 100V

250 - 200V

350 - 400V

450 - 500V

C50 - 600V

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